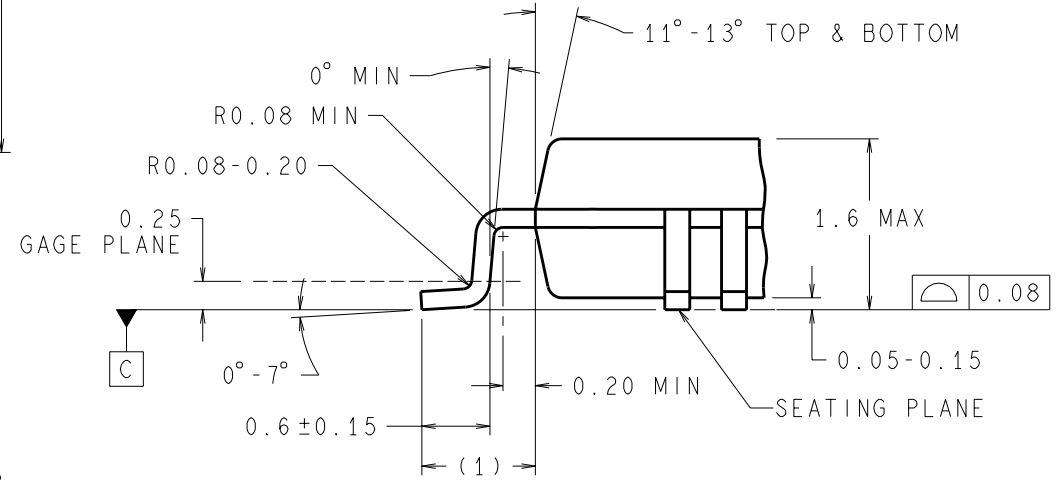
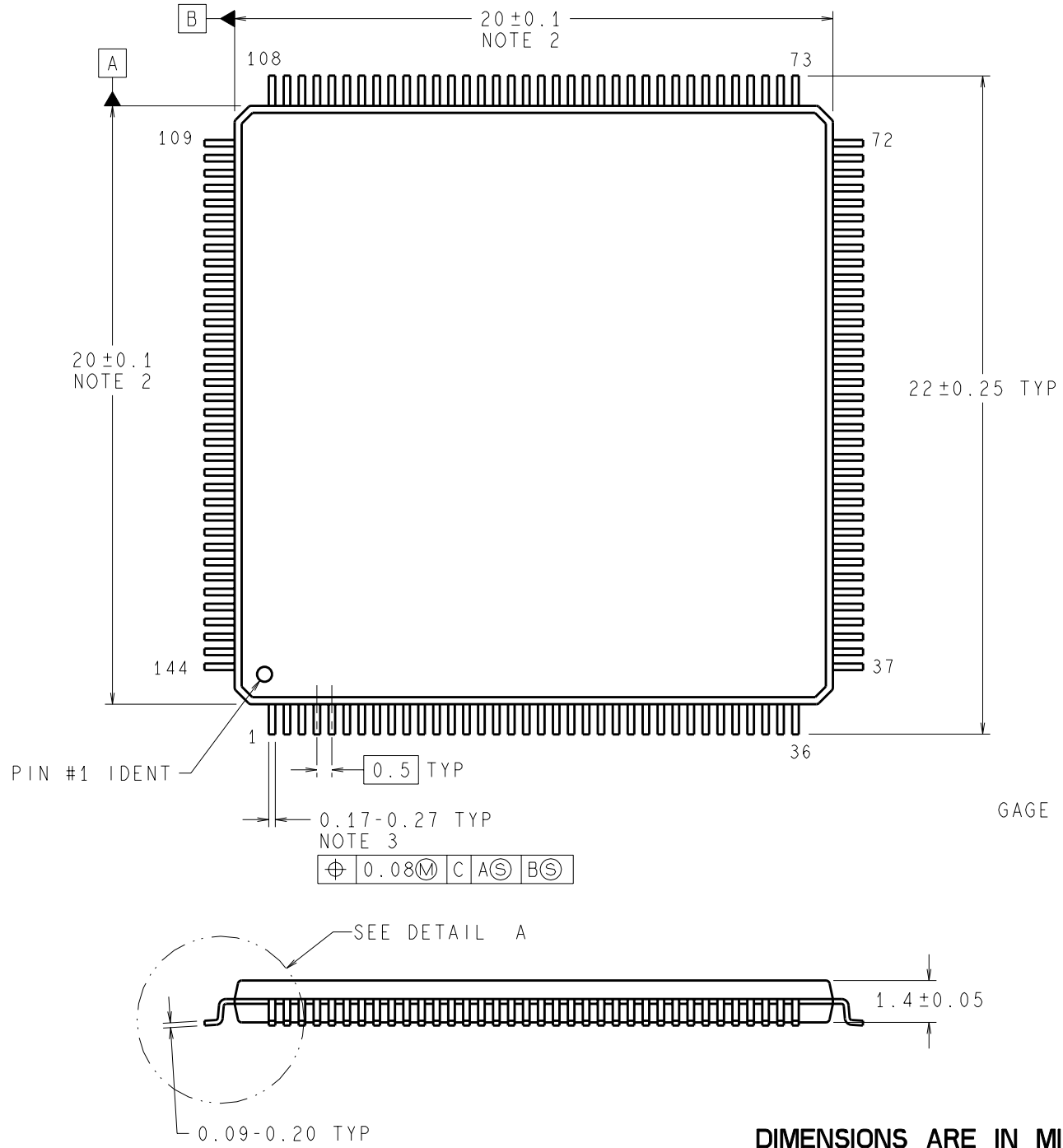


REVISIONS				
LTR	DESCRIPTION	E.C.N.	DATE	BY/APP'D
E	REVISE & REDRAW PER NEW STANDARDS	11063	07/13/1995	DEG/RRR
F	TITLE: LQFP WAS PQFP; UPDATE NOTE 4; ADD GEOMETRIC TOLERANCE	12317	11/10/1999	TL/RW



DETAIL A
TYP, SCALE: 25X

DIMENSIONS ARE IN MILLIMETERS

NOTES: UNLESS OTHERWISE SPECIFIED

- STANDARD LEAD FINISH:
7.62 MICROMETERS MINIMUM SOLDER PLATING (85/15)
THICKNESS ON ALLOY 42 / COPPER.
- DIMENSION DOES NOT INCLUDE MOLD PROTRUSION.
MAXIMUM ALLOWABLE MOLD PROTRUSION 0.25mm PER SIDE.
- DIMENSION DOES NOT INCLUDE MOLD PROTRUSION.
ALLOWABLE BAMPBAR PROTRUSION SHALL BE 0.08.
- REFERENCE JEDEC REGISTRATION MS-026, VARIATION BFB,
DATED FEBRUARY 1999.

APPROVALS	DATE	National Semiconductor			
DRAWN D.E. Grady	07/10/95	2900 Semiconductor Dr., Santa Clara, CA 95052-8090			
DFTG. CHK. MARTA SUCHY	11/10/1999	LQFP, JEDEC METRIC, 20 X 20 X 1.4mm, 144 LEAD			
ENGR. CHK. RANDY WALBERG	11/10/1999				
PROJECTION		SCALE	SIZE	DRAWING NUMBER	REV
		N/A	C	(SC)MKT-VNG144A	F
		FORMERLY: N/A	SHEET 1 of 1		